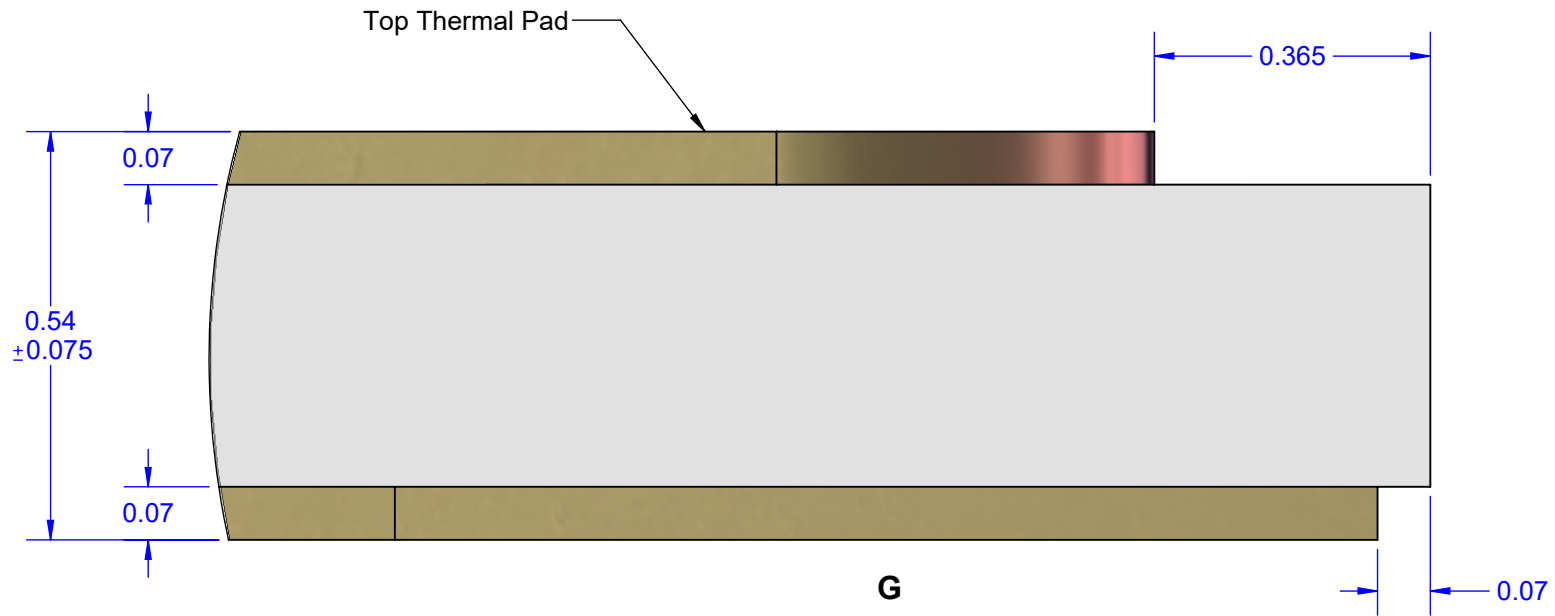


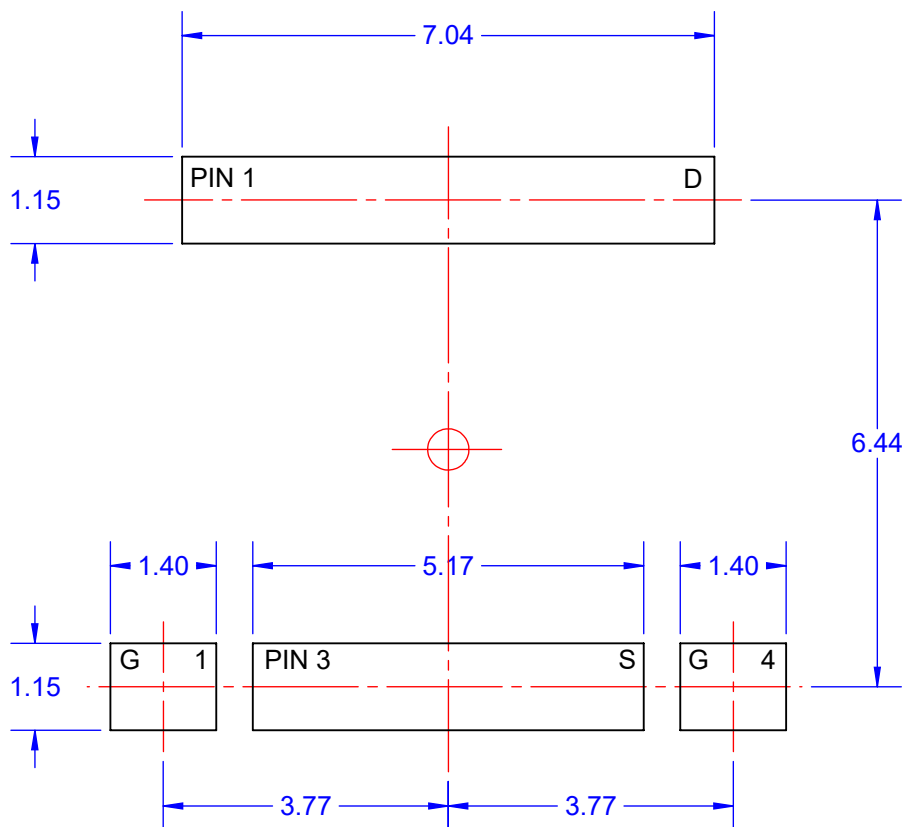
DETAIL A



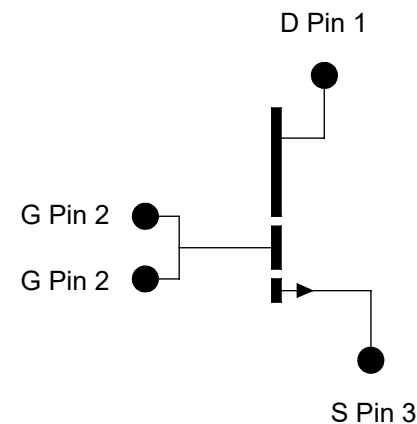
NOTES: (Unless Otherwise Stated)
 1. DIMENSIONS mm.

TopLine[®]			
TITLE QFN4-TDG650E60T TOP COOLED DUMMY PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
100:1	A	494650	A
DO NOT SCALE DRAWING			SHEET 2 OF 5

RECOMMENDED MINIMUM FOOTPRINT PCB LAND PATTERN



REFERENCE ONLY SYMBOL CIRCUIT



NOTES: (Unless Otherwise Stated)

1. DIMENSIONS mm PRESENTED ONLY AS A GUIDELINE.
2. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE WHEN DESIGNING THE PCB.
3. TYPICAL PCB IS 4-LAYER FR4 WITH 2-oz. COPPER ON EACH LAYER.
4. SYMBOL CIRCUIT FOR REFERENCE ONLY: D = DRAIN, G = GATE, S = SOURCE.
5. DUMMY PACKAGE IS NOT ELECTRICALLY FUNCTIONAL.
6. PACKAGE MOISTURE SENSITIVITY LEVEL MSL-3.
7. SOLDER PASTE STENCIL THICKNESS 100 μ m (4-MIL).
8. SOLDER PASTE COVERAGE 70%.

TopLine[®]

TITLE QFN4-TDG650E60T
TOP COOLED DUMMY PACKAGE

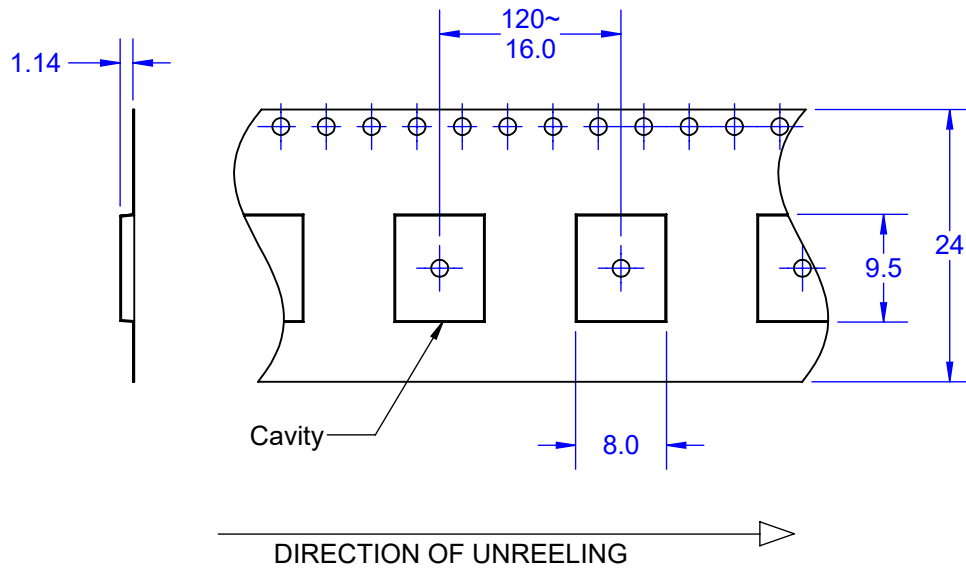
SCALE	SIZE	DRAWING NO.	REV
10:1	A	494650	A

DO NOT SCALE DRAWING

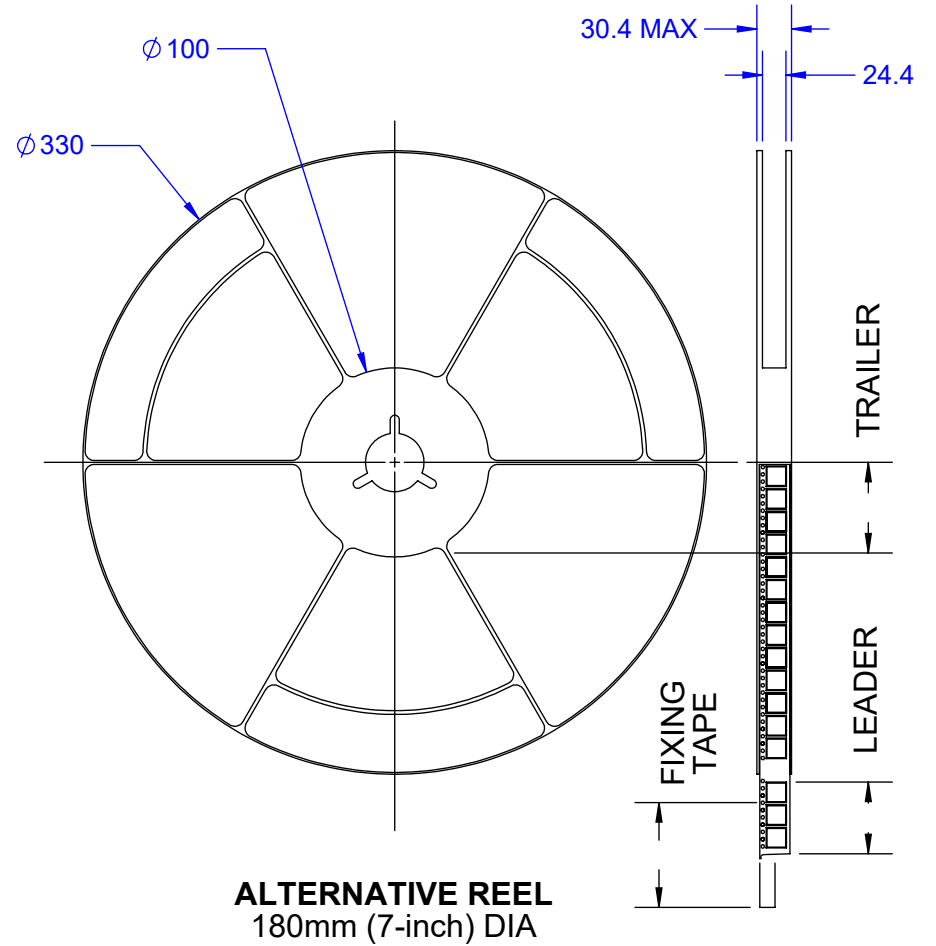
SHEET 3 OF 5

TAPE SPECIFICATION QFN4-TDG650E60T-E SURFACE MOUNT DEVICE

TAPE DIMENSIONS



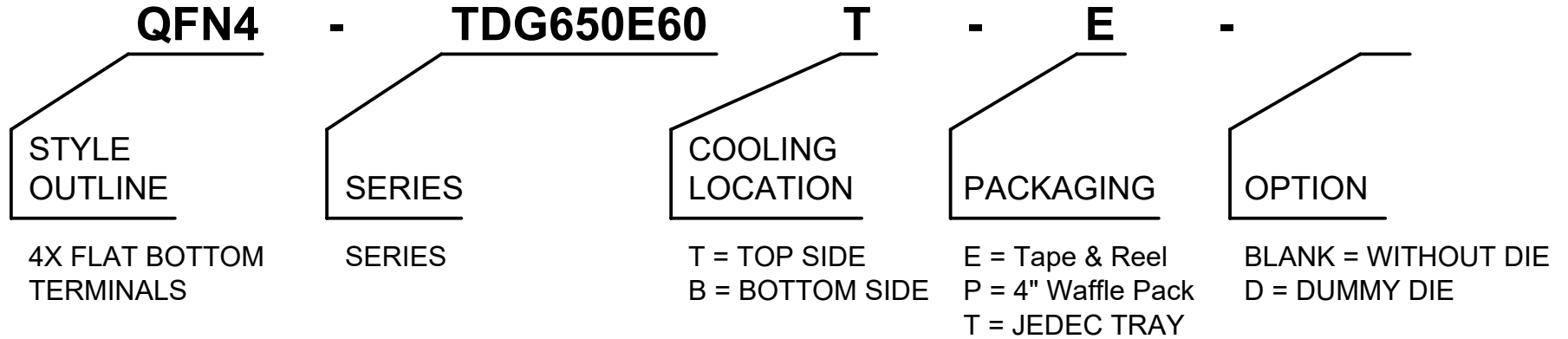
PACKAGE REEL



ALL DIMENSIONS IN mm.

TopLine[®]			
TITLE QFN4-TDG650E60T TOP COOLED DUMMY PACKAGE			
SCALE 3:2	SIZE A	DRAWING NO. 494650	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 5	

PART NUMBERING SYSTEM



PART NUMBER	DAISY CHAIN	PACKAGING	RoHS Pb-FREE	PLATING	DUMMY DIE
QFN4-TDG650E60T-E	NO	REEL	YES	ENIG	NO
QFN4-TDG605E60T-P	NO	CHIP TRAY	YES	ENIG	NO

OTHER PART NUMBER CONFIGURATIONS AVAILABLE. CONTACT TOPLINE.

NOTES:

ENIG = ELECTROLESS NICKEL, IMMERSION GOLD.

TopLine[®]			
TITLE QFN4-TDG650E60T TOP COOLED DUMMY PACKAGE			
SCALE NONE	SIZE A	DRAWING NO. 494650	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 5